

PMT Orders Maskless Lithography System from EVG for Wafer Probe Card Manufacturing – January 25, 2024

semiconductor packaging news

News Focused on Semiconductor Packaging

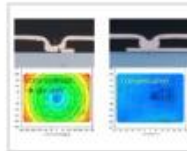
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January 25, 2024

Fan-Out Panel-Level Packaging Hurdles

The semiconductor industry faces significant challenges in fan-out panel-level packaging, as highlighted in a recent news story. These hurdles involve issues related to cost, technology, and scalability, impacting the development of advanced packaging solutions.

Semiconductor Engineering



Epoxy for Medical Device Applications

Master Bond EP40TCMed epoxy meets the requirements of ISO 10993-5 for non-cytotoxicity. It is a thermally conductive and electrically insulative system.

Master Bond



VIEWPOINT 2024: Anika Baumhauer, International Strategy & Sales Manager, SONOTEC GmbH

We see continued growth in the semiconductor market. The year 2023 has been tough and challenged us a lot, but we also received a great amount of encouragement and positive feedback from global semiconductor players and research institutes. Increasing material prices, the ongoing uncertainty in the supply chains ...

SONOTEC GmbH



How to Select RF Test Socket

Selecting the right RF test socket involves several factors – frequency, insertion loss, return loss, impedance matching, contact force, contact resistance, durability ...

Technical Paper

Coal: Don't Burn It, Compute With It

The IEEE Spectrum reports on promising developments in silicon semiconductor alternatives, highlighting the pursuit of more sustainable and efficient materials to replace coal in the semiconductor manufacturing process, potentially reducing environmental impact.

IEEE Spectrum

Technical Papers

- Highly Selective Epoxy Molding Compound Removal in Advanced Semiconductor Devices
- Motivation for pressure-assisted metallic sintering in Power Electronics
- IR Laser Cleave Technology for 3D Packaging and Logic Scaling
- Next Gen Laser Assisted Bonding (LAB) Technology
- Durability and Cost Benefits Drive Mil-Aero Demand for QCPP
- Revising 5G RF Calibration Procedures For RF IC Production Testing
- Optimizing New Power Switch Technology Using Compound Semiconductors

Targeted Sample Preparation for Deeply Buried ROI in Advanced Packages

New fault isolation technique using 3D X-ray microscopy & LaserFIB to pinpoint, isolate & open a 20 µm wirebond without damage to adjacent wires.

ZEISS Microscopy



Buy Ceramic Dispensing Needles Online

Ceramic needles with Luer Lok for conductive epoxies and encapsulation. The ceramic molding process allows for smaller more precise inner diameters with a glass like finish. Buy Online.

DL Technology



Large Capacity Plasma Treatment System - FlexTRAK-SHS

9.6-liter plasma process chamber handles larger, or more, strips increasing throughput and productivity for electronics/semiconductor packaging.

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Today's Sponsor



Test Your Knowledge

If you drop a 5 when rounding a number, you are using the (a) round-to-even rule; (b) significant digit rule; (c) round-off rule; (d) retained digit rule

See answer below.



Press Releases

PMT Orders Maskless Lithography System from EVG for Wafer Probe Card Manufacturing

PROTEC MEMS Technology (PMT) has ordered a LITHOSCALE® maskless exposure system from EV Group (EVG), a leading supplier of wafer bonding and lithography equipment ...

EV Group

Laser Thermal Partners with Angstrom Scientific, Inc. for Sales Representation

Laser Thermal is pleased to announce the signing of Angstrom Scientific as its newest representative for sales of the company's flagship SSTR-F (Steady State Thermoreflectance ...

Laser Thermal

Indium Corporation Expert to Present at INEMI Seminar Hosted by Zestron Europe

Indium Corporation Regional Technical Manager and Technologist – Advanced Applications Andreas Karch will present at INEMI's upcoming seminar, Humidity Robustness and Isolation ...

Indium Corporation

Koh Young Shares Revolutionary Advanced Package Inspection Solutions at the SMTA WLP

Koh Young Technology will be speaking at the SMTA Wafer-Level Packaging Symposium in Burlingame, California on our Multimodal Phase Shift Optics Approach to revolutionize ...

Koh Young Technology

Critical chip firm ASML posts 30% surge in full-year revenue but signals slowdown in 2024

ASML, a leading semiconductor equipment manufacturer, has reported its Q4 and full-year 2023 earnings. The company exceeded expectations, posting strong financial results amidst the global chip shortage, demonstrating its resilience in the semiconductor industry.

CNBC

ASML annual profits surge to US\$8.5bn

ASML Holding NV, the Dutch tech giant supplying chipmaking machines, posted a robust annual net profit of 7.8 billion euros (\$8.5 billion), up from 5.6 billion euros, defying China-West trade tensions.

Taipei Times

Canada Must Double Down on Chip Industry Talent

Canada is urged to ramp up efforts in nurturing talent within its semiconductor industry as global chip demand continues to soar. Strengthening the nation's tech workforce is essential for its competitiveness in this critical sector.

EE Times

EVG
NEXT-GENERATION FUSION AND HYBRID BONDING
EVG Fusion and Hybrid Bonding Solutions, Expertise and Competence Center Accelerate Heterogeneous Integration Technology
CLICK HERE TO LEARN MORE

plasmatech
Openair-Plasma®
for flux-free oxide reduction
Click here for more

PacTech
Chip Assembly & Solder Rework
Laplace Systems www.pacotech.de

Alphabet cuts ties with Australian AI firm that helped train Bard and Google Search

Alphabet, Google's parent company, terminates its contract with Appen, a key player in training its search engine, Bard. This move marks a significant shift in Alphabet's strategy for enhancing its search capabilities.

CNBC

Texas Instruments posts disappointing guidance, signaling weakness in chip industry

Texas Instruments' positive sales revenue guidance for the semiconductor industry signals optimism amid global chip shortages. The company's strong performance reflects resilience in the sector, offering hope for continued growth.

Digitimes

Alternatives to Isopropyl Alcohol (IPA)
Having a hard time finding IPA? KYZEN offers safe, affordable alternatives globally! To learn more, fill out this form to download our technical brief!
KYZEN

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TSMC Expansion Augurs Well for Chip Industry

TSMC's expansion plans hold promise for the AI chip supply chain. The semiconductor giant's growth strategy is poised to meet the rising demand for AI-related technologies, ensuring a steady and robust supply.

EPS News

Nvidia CEO's low-key China visit seen as a goodwill gesture towards key market as US chip firm grapples with sanction issues

NVIDIA CEO's recent visit to China is viewed as a goodwill gesture toward a crucial market. The US chip giant seeks to strengthen ties amidst challenges in the tech war.

South China Morning Post

Koh Young America, Inc.

Particle-Free Plasma Oxide Reduction

Ar/H₂ plasma for flux-free flip chip bonding. Low temp, uniform 100 mm wide beams. Fast oxide removal. No damage or particles. Contact us for integration into your TCB bonder.
Surfx Technologies



Quote of the Day

"You only have to do a very few things right in your life so long as you don't do too many things wrong."

Warren Buffett

Die Attach Material Comparisons

Packaging high-power GaN devices? This study compares CuW and CMC bases with H₂O₂ and AuSn, revealing 34.5°C cooler junctions with CMC/AuSn. Revolutionize GaN efficiency/reliability.
Stratedge Corporation



2024 IEEE 74th ECTC Conference

The ECTC conference is the premier international event that brings together the best in packaging, components & microelectronic systems science, technology & education, May 28-31.
ECTC



The day was Jan 25. What year was it?

World's Largest Diamond Found

At the Premier Mine in Pretoria, South Africa, a 3106-carat diamond is discovered during a routine inspection. It was the largest diamond ever found.
See the answer below.



Plasma Etch

Thin Is In

This article discusses market drivers & technical challenges related to handling & working with ultra-thin devices. Being able to robustly and safely remove thin die from tape is a key requirement.
Royce Instruments



Cartoon of the Day





"Everyone laughed and called me a fool, but I've spent the past 30 years watching my helium stocks go up!"
Copyright © Randy Glasbergen



Calendar

- [Jan 25, 2024: FOA Q1 Collaborative Forum](#)
- [Jan 31, 2024: SEMICON Korea](#)
- [Feb 13, 2024: SMTA Wafer-Level Packaging Symposium](#)
- [Mar 20, 2024: SEMICON CHINA](#)

Alternatives to Isopropyl Alcohol (IPA)

Having a hard time finding IPA? KYZEN offers safe, affordable alternatives globally! To learn more, fill out this form to download our technical brief!
KYZEN



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Test Your Knowledge Answer

If you drop a 5 when rounding a number, you are using the (a) round-to-even rule; (b) significant digit rule; (c) round-off rule; (d) retained digit rule

Answer: (a) round-to-even rule

What Year Was It Answer

World's Largest Diamond Found
Answer: January 25, 1905

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Circuitnet Media, LLC

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